

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT																		
NATURE OF CONVEYANCE:	ASSIGNMENT																		
CONVEYING PARTY DATA																			
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr><td>Kazuya SEKIGUCHI</td><td>08/27/2008</td></tr> <tr><td>Yoshio FUKAYAMA</td><td>08/27/2008</td></tr> <tr><td>Yuji TAKAHASHI</td><td>08/27/2008</td></tr> <tr><td>Tomokuni CHINO</td><td>08/27/2008</td></tr> <tr><td>Tsuyoshi KACHI</td><td>08/27/2008</td></tr> <tr><td>Katsuhiro MITSUI</td><td>08/27/2008</td></tr> <tr><td>Daisuke ONO</td><td>09/01/2008</td></tr> <tr><td>Tatsuhiko MIURA</td><td>08/28/2008</td></tr> </tbody> </table>		Name	Execution Date	Kazuya SEKIGUCHI	08/27/2008	Yoshio FUKAYAMA	08/27/2008	Yuji TAKAHASHI	08/27/2008	Tomokuni CHINO	08/27/2008	Tsuyoshi KACHI	08/27/2008	Katsuhiro MITSUI	08/27/2008	Daisuke ONO	09/01/2008	Tatsuhiko MIURA	08/28/2008
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr><td style="width: 20%;">Name:</td><td>Renesas Technology Corp.</td></tr> <tr><td>Street Address:</td><td>6-2, Otemachi 2-chome, Chiyoda-ku</td></tr> <tr><td>City:</td><td>Tokyo</td></tr> <tr><td>State/Country:</td><td>JAPAN</td></tr> </table>		Name:	Renesas Technology Corp.	Street Address:	6-2, Otemachi 2-chome, Chiyoda-ku	City:	Tokyo	State/Country:	JAPAN										
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CORRESPONDENCE DATA																			
<p>Fax Number: (703)610-8686</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 7036108652</p> <p>Email: dminter@milesstockbridge.com</p> <p>Correspondent Name: Mitchell W. Shapiro</p> <p>Address Line 1: 1751 Pinnacle Drive, Suite 500</p> <p>Address Line 4: McLean, VIRGINIA 22102-3833</p>																			
ATTORNEY DOCKET NUMBER:	XA-11196/T3844-15795US01																		

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PATENT
REEL: 022091 FRAME: 0815

NAME OF SUBMITTER:

Mitchell W. Shapiro

Total Attachments: 1

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ASSIGNMENT

(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Technology Corp., a corporation organized under the laws of Japan, located at 6-2, Otemachi 2-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Technology Corp., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

A SEMICONDUCTOR DEVICE AND A METHOD OF MANUFACTURING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Renesas Technology Corp., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Technology Corp.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) Kazuya SEKIGUCHI	Kazuya SEKIGUCHI	27 / August / 2008
2) Yoshio Fukayama	Yoshio FUKAYAMA	27 / August / 2008
3) Yuji Takahashi	Yuji TAKAHASHI	27 / August / 2008
4) Tomokuni CHINO	Tomokuni CHINO	27 / August / 2008
5) Tsuyoshi Kachi	Tsuyoshi KACHI	27 / August / 2008
6) Katsuhiko Mitsui	Katsuhiko MITSUI	27 / August / 2008
7) Daisuke Ono	Daisuke ONO	1 / September / 2008
8) Tatsuhiko Miura	Tatsuhiko MIURA	28 / August / 2008
9)		
10)		

PATENT

RECORDED: 01/12/2009

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